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Please replace the title of the invention with the following new title:

METHOD FOR SEPARATING A MASK FROM THE SURFACE OF A SEMICONDUCTOR
WAFER.

Please replace paragraph [0022] with the following amended paragraph:

ABSTRACT OF THE DISCLOSURE

[0022] ~~Computer controlled de-clip shadow mask removal machine. The present disclosure describes a computer controlled, fully programmable de-clip shadow mask removal method and system. This A method for separating a mask from the surface of a semiconductor wafer comprises first mounting a mask/wafer combination on a rotatable surface and then rotating the rotatable surface. A separating device is inserted at the edge of the mask between the two mating surfaces of the mask and the semiconductor wafer. The semiconductor device is then urged upward toward the rotating center of the mask/wafer combination while the rotatable surface is rotating, and system is adapted to remove retaining clips (without human contact), separate a shadow mask from a semiconductor wafer after a metal evaporation process, and then remove the shadow mask with greater accuracy. The system uses servomotors which precisely control all ranges of motion required to safely and efficiently remove the mask from the wafer thus minimizing potential damages incurred by human contact.~~

AMENDMENT AND RESPONSE
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